

### **Remarks**

Applicants have amended claims 1 and 27; and canceled claim 24. Support for Applicants' amendment can be found, for example, with reference to FIGS. 4-7 of the present application. No new matter has been added to the application by virtue of the present amendments.

### **Claim Rejections - 35 U.S.C. § 103(a)**

The Examiner rejected claims 1-6, 8, 22, 23 and 25 under 35 U.S.C. § 103(a) as being unpatentable over Baba, U.S. Patent No. 6,313,521 in view of Hoffman, U.S. Patent No. 6,630,661.

Applicants have amended claim 1 to include the limitations of dependent claim 24 (now canceled). Applicants respectfully submit that Baba in view of Hoffman does not disclose, teach or suggest Applicants' claim 1, as amended, i.e. "... a conductive block having about the same dimensions as a surface mount technology (SMT) discrete chip component ..." or "...said conductive block provides for said semiconductor package to be **stiffener-free**" (emphasis added). Baba discloses a semiconductor package which includes a stiffener board 10 and Baba is silent on disclosing a semiconductor package which does not include a stiffener board 10. Support for Applicants' amendment can be found, for example, with reference to FIGS 4-7 which show that by using a conductive block as claimed in the present invention, a stiffener is not required in the semiconductor packages shown in the FIGS. 4-7.

Therefore, Applicants respectfully traverse the rejection under 35 U.S.C. § 103(a) and submit that the rejections to claims 1-6, 8, 22, 23 and 25 have been overcome.

### **Claim Rejections - 35 U.S.C. § 103(a)**

The Examiner rejected claims 1, 10 and 24 under 35 U.S.C. § 103(a), as being unpatentable over Jimarez et al., U.S. Patent No. 6,407,334 in view of Hoffman, U.S. Patent No. 6,630,661; and

claims 27-33 under 35 U.S.C. § 103(a), as being unpatentable over Jimarez et al., U.S. Patent No. 6,407,334 in view of Hoffman and Glenn et al, U.S. Patent No. 6,562,655).

Applicants have amended independent claims 1 and 27 to include the limitation of “... said semiconductor package to be **stiffener-free**” (emphasis added). Jimarez fails to disclose, teach or suggest Applicants’ claims 1 and 27, as amended. Jimarez discloses a semiconductor package which comprises a “stiffener member 26”. Jimarez is silent on a semiconductor package which does not include a stiffener. Hoffman and/or Glenn do not remedy the deficiencies in Jimarez.

Therefore, Applicants respectfully traverse the rejection under 35 U.S.C. § 103(a) and submit that the rejections to the claims have been overcome.

### **Conclusion**

In light of the foregoing remarks and amendments, all of the claims now presented are believed to be in condition for allowance, and Applicants respectfully request that the outstanding rejections be withdrawn and this application be passed to issue at an early date.

The Examiner is urged to call the undersigned at the number listed below if, in the Examiner's opinion, such a phone conference would aid in furthering the prosecution of this application. A fee for a one month extension of time is due by virtue of this response. If the PTO determines that any other fee is required, please charge Applicants' Deposit Account, 09-0456.

Respectfully submitted,

For: Michael Gaynes, et al.

By: /Anthony J. Canale/

Anthony J. Canale

Registration No. 51,526

Telephone No.: (802) 769-8782

Fax No.: (802) 769-8938

EMAIL: [acanale@us.ibm.com](mailto:acanale@us.ibm.com)

International Business Machines Corporation  
Intellectual Property Law - Mail 972E  
1000 River Road  
Essex Junction, VT 05452